BGA Heat Sink - High Performance maxiFLOW/superGRIP-Low-Profile





ATS Part#: ATS-X51330R-C1-R0

Description: 33.00 x 33.00 x 19.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP-

Low-Profile

Heat Sink Type: maxiFLOW

Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

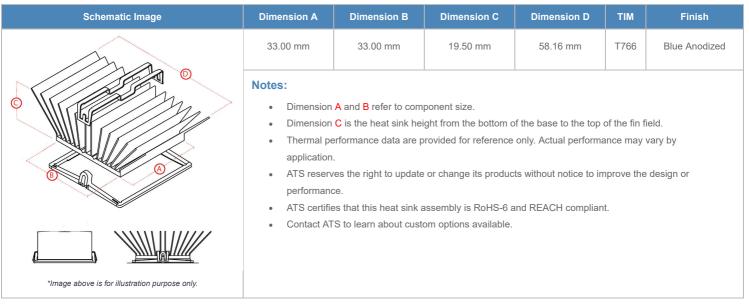
Features & Benefits

- · Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- · Strong, uniform attachment force helps achieve maximum performance from phase-change TIMs
- · Eliminates the need to drill mounting holes in the PCB
- Assembly comes standard with a high performance maxiFLOW™ heat sink, which maximizes convection (air) cooling. Please refer to the superGRIP™ Keep-Out Guidelines and superGRIP™ Installation/Removal Guide for further details
- Comes standard with clean break, reworkable, Chomerics T-766 phase change material
- Designed for standard height components, from 1.5 to 2.9 mm

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	2.6 °C/W	2.1 °C/W	1.8 °C/W	1.7 °C/W	1.5 °C/W	1.4 °C/W	1.3 °C/W
	Ducted Flow	2.0	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.



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